

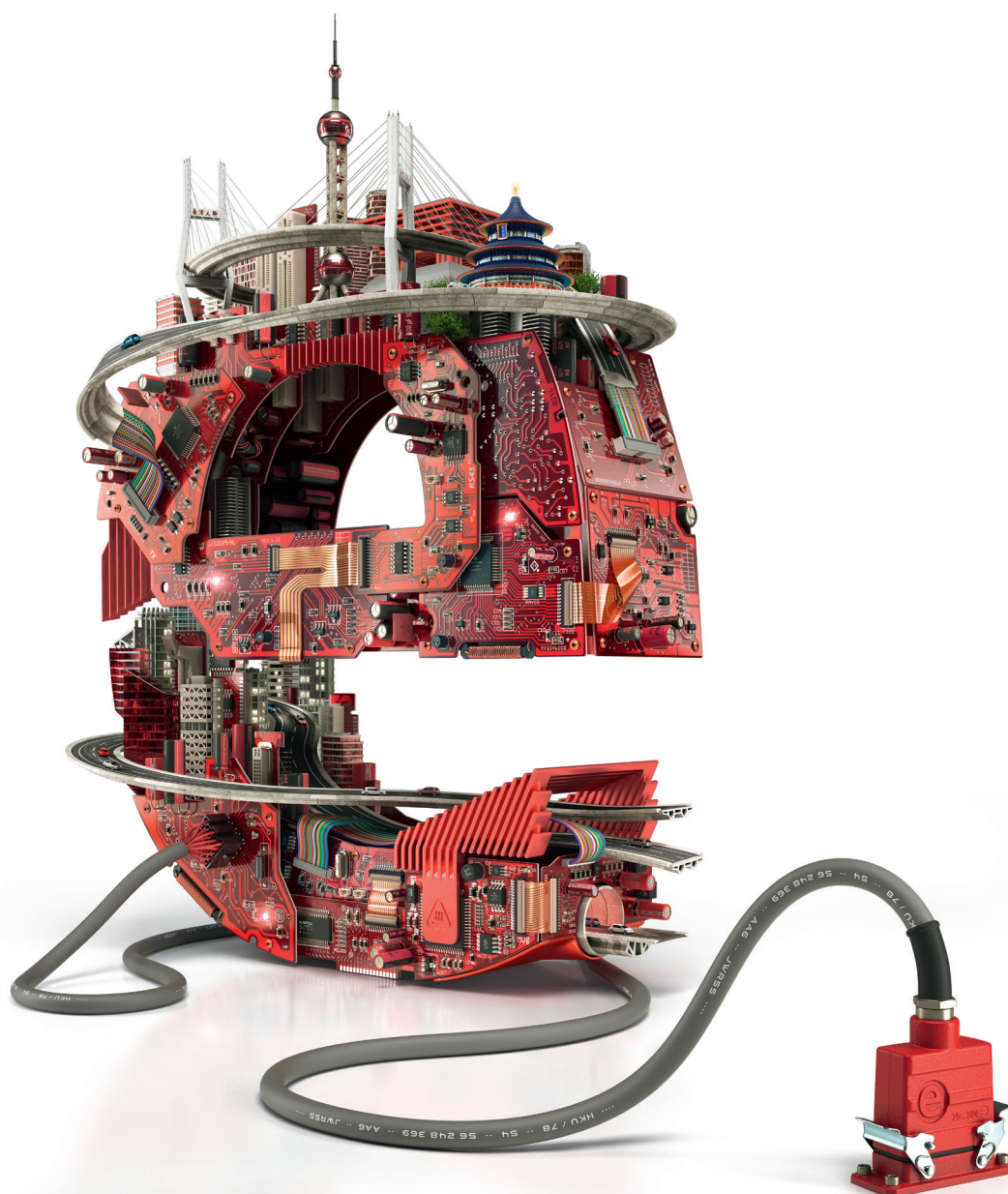


Messe München

Connecting Global Competence

International Embedded System Innovation Forum

Fusion, ushering a smart future



March 18–20, 2020

Shanghai New International Expo Centre

electronica-china.com



electronica China

General Information



Date:

March 19th, 2020



Venue:

Room M31 in Hall E5 (2nd Floor)



Organizer:

Messe München Shanghai Co., Ltd.



Material Submission Deadline:

- Bilingual info of subject and speaker, presentation abstract of 250 words: December 31, 2019

- Complete PPT submission: January 30, 2020



Language:

Chinese or English, no simultaneous interpretation
(Non-Chinese speakers are recommended to use bilingual slides)

Topics

- Artificial Intelligent (AIoT and Embedded Vision)
- Internet of Things (5G and IoT Security)

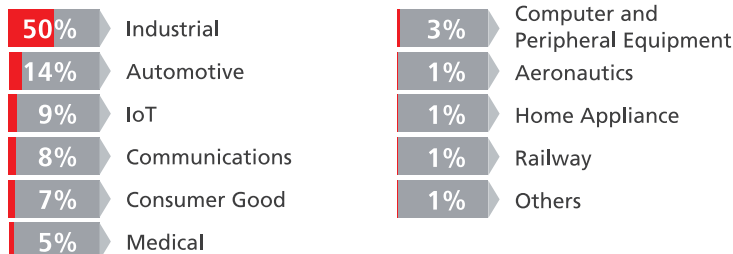
2019 Audience analysis

Attendance audience: **398**

By Job function



By Industry



2019 Sample List

Chery Technical Center Shanghai (CTCS)
Dongfeng Electric Drive Systems Co., Ltd.
Nexteer Automotive Group Ltd.
Yanfeng Visteon Automotive Electronics Co., Ltd.
Sunplus Technology Co., Ltd.
Honorsun (Xiamen) Data Co., Ltd.
BSH Home Appliances Co., Ltd.
Panasonic Home Appliances R&D Center (Hangzhou) Co., Ltd.
Daikin R&D Center
Zhejiang ZhiXuan Sci-tech Co., Ltd.
Shanghai Moopiot Co., Ltd.
PINS Medical Co., Ltd.
Hangzhou Nenglian Sci-tech Co., Ltd.
Alibaba Group
vivo Mobile Communication Co., Ltd.
Shanghai Oriental Pearl Group Co., Ltd.
Ericsson (China) Communications Co., Ltd.
Zhongtian Broadband Technology Co., Ltd.
Quectel Wireless Solutions Co., Ltd.
United Technologies Research Center(China) Ltd.
SANHUA HOLDING GROUP
Siemens Industry Software(Shanghai) Co., Ltd.
Schneider Electric
Shanghai United Imaging Healthcare Co., Ltd.
I SEE HEALTH Co., Ltd.
Xilinx, Inc.
UNISOC TECHNOLOGIES INC.

2019 Speaker Team



MCU and Embedded
System Application
Journal

Allan He
Deputy Director
of Editorial Board



Cambricon

Tao Luo
Vice-president



Thundersoft

Pengcheng Zou
CTO



South China University of
Technology Associate

Sheng Bi
Professor



NXP

Yi Fang
Marketing Manager



Arm

Liming Li
Regional Marketing
Manager, IoT & Embedded
Vice-president



Analog Devices
Shanghai Inc.

Fan Wang
Application Engineer



Rohde & Schwarz International

Merdan Elbistan
Regional Manager



Nanchang University

Wufei Wu
Assistant professor

Forum sponsorship packages

Benefits	Platinum Sponsor CNY 50,000	Gold Sponsor CNY 35,000
■ During the show		
Slot price (about 30 min, including Q&A)	✓	✓
Poster / Roll-up (production excluded)	✓	✓
Logo on backdrop	✓	✓
Gift Sponsorship (production excluded and distribution time arranged by organizer)	✓	✓
Speech Brochure distribution	✓	✓
Advertisement on the Visitor Guide (it is free of charge and nearly every visitor who attends the fair uses it to have a better orientation)	Inside page, 1/1 (4c)	Inside page, 1/2 (4c)
Sponsors' advertising video will be shown during lunch time or before the forum (five mins at most, only two exhibitors)	✓	
Desktop exhibit	✓	
■ Before the show		
Newsletter with the information of sponsor (more than twice)	✓	✓
Speech information promotion on the WeChat group	✓	✓
Speech information promotion on the conference page of official website	✓	✓
Tailor-made email delivery (once)	✓	
Press release publish via WeChat (once)	✓	
Banner on conference webpage	✓	

Single sponsorship

Benefits	Price
Slot price (about 30 min, including Q&A)	CNY 25,000
Tailor-made email deliveries to the pre-registrants	CNY 3,000
Logo on backdrop	CNY 5,000
Desktop exhibit, one table per sponsor (placed outside the venue)	CNY 8,000
Gift Sponsorship (production excluded)	CNY 3,000
Poster / Roll-up (production excluded)	CNY 3,000
Speech Brochure distribution (production excluded)	CNY 5,000
Conference stationery sponsorship (production excluded)	CNY 5,000
Tote bag sponsorship (production excluded)	CNY 5,000

Contact

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